

LC series

Backside Coating Tape

Adwill LC Tape was developed as an alternative to liquid mold material. Its function is to protect and reinforce the die backside in applications like Flip Chip, in which the die is mounted onto a substrate from the circuit surface. While protecting and reinforcing the die backside, it also blocks light to minimize damage to the circuit surface. Unlike when coating with liquid mold material, this product is available as a tape, ensuring outstanding uniformity in thickness and allowing the simplification of conventional processes.

Featuring both high quality and stability, the tape has passed reliability tests in environments of high temperature and humidity.

LC Tape is suitable for back-side laser-marking and back-side chipping inspection through tape by using IR.

Marking LINTEC's newest development, latest LC Tape versions are also available in pre-cut format.



Application	Dicing Method	LC-Layer Thickness	Type	Tape Name
IR-Shielding, high reliability	Blade	25 µm, 40 µm	Roll	LC88 Series
	Blade		Pre-Cut	LC88R Series
IR-Transmissive, high reliability	Blade	25 µm, 40 µm	Roll	LC28x6 Series
	Blade		Pre-Cut	LC86R Series
Stealth-Dicing, high reliability	Stealth-Laser	25 µm	Roll	LC87-25